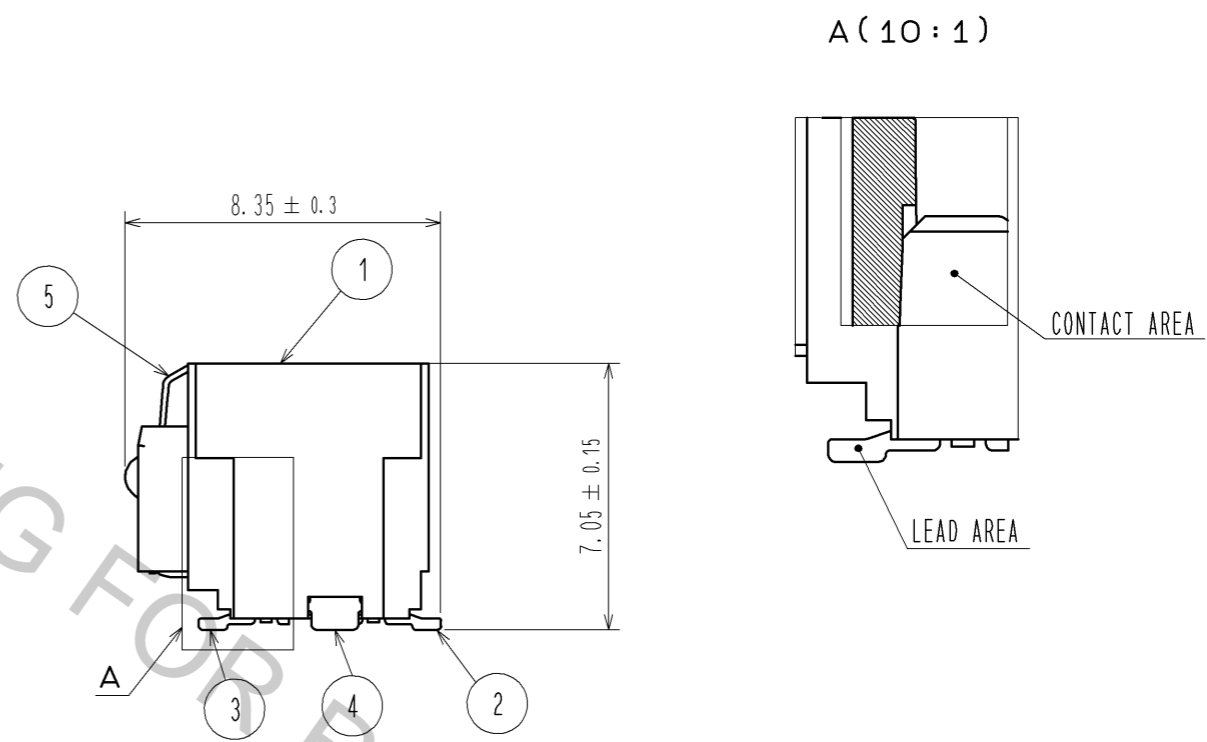
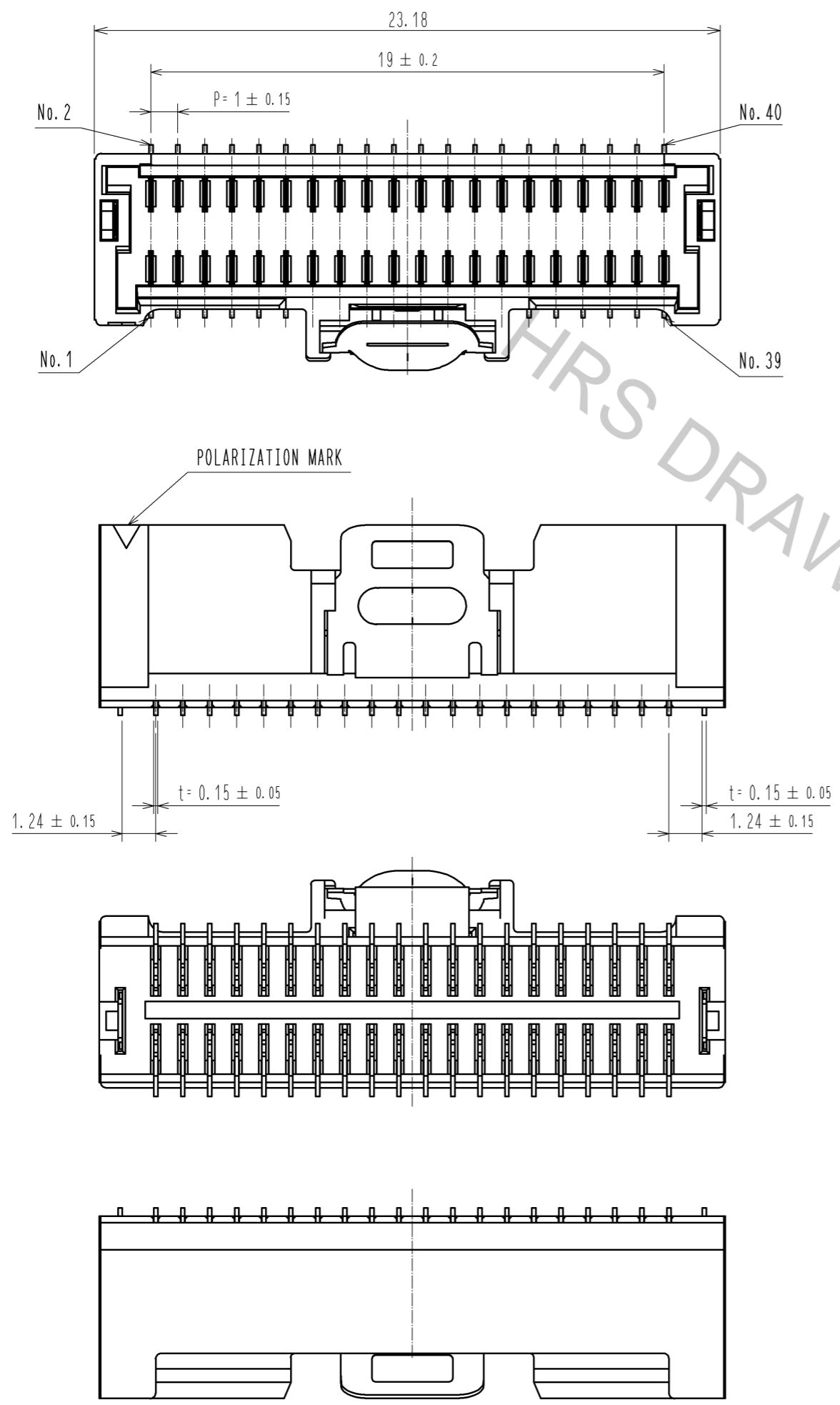


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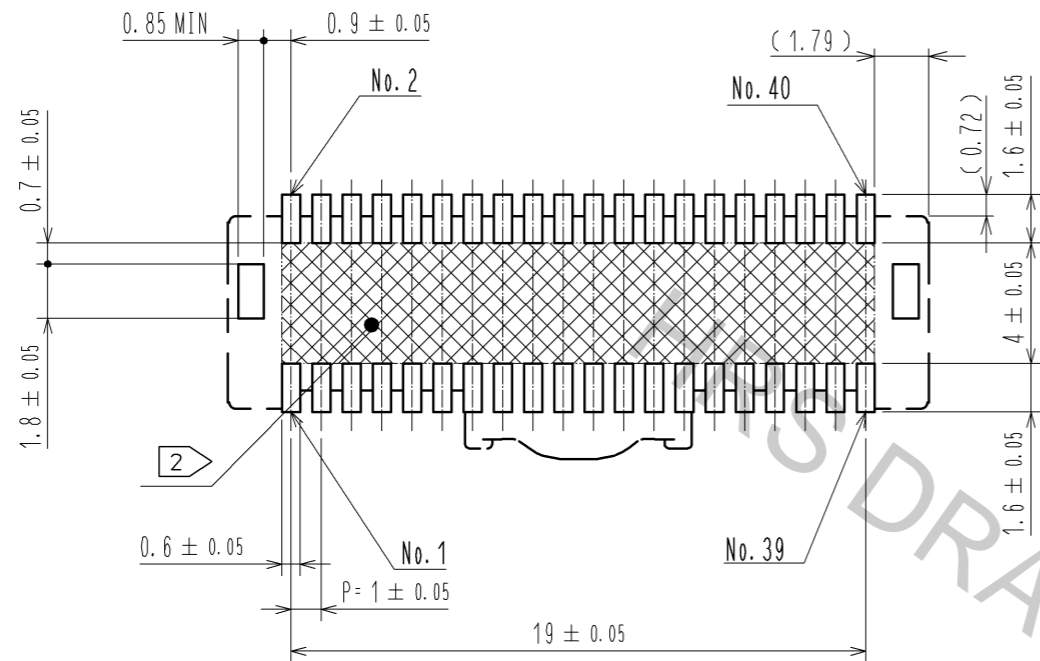


NOTES
 1. LEAD CO-PLANARITY SHALL BE 0.1 mm MAX.
 2. AREA INDICATED MUST BE FREE OF CONDUCTIVE TRACES OR THE CONDUCTIVE TRACES MUST BE COVERED BY RESIST FILM.
 3. PLEASE CONSULT HIROSE WHEN THE PRODUCT IS MOUNTED TO EPC.

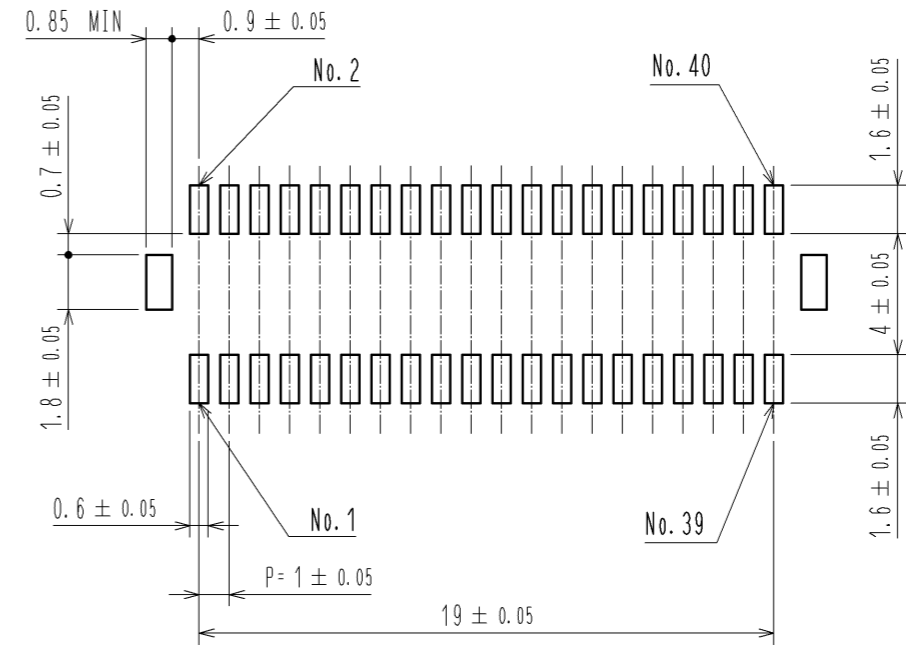
3	BRASS	CONTACT AREA : Au PLATING 0.05μm MIN.	9	POLYAMIDE	VACUUM CAP
		LEAD AREA : Au PLATING 0.05μm MIN.	8	PS	REEL, BLACK
2	BRASS	UNDERPLATING : Ni PLATING 1μm MIN.	7	POLYESTER	CLEAR
		CONTACT AREA : Au PLATING 0.05μm MIN.	6	PS	CLEAR
1	LCP	LEAD AREA : Au PLATING 0.05μm MIN.	5	STAINLESS STEEL	-
		UNDERPLATING : Ni PLATING 1μm MIN.	4	BRASS	SURFACE : Sn PLATING 1μm MIN. UNDERPLATING : Ni PLATING 0.5μm MIN.
NO. MATERIAL FINISH . REMARKS		NO. MATERIAL FINISH . REMARKS			
UNITS mm		SCALE FREE	COUNT 	DESCRIPTION OF REVISIONS	DESIGNED
APPROVED : KI. AKIYAMA 14.10.24			DRAWING NO. EDC3-324909-04		
CHECED : TS. FUKUSHIMA 14.10.24			PART NO. DF50-40DP-1V(62)		
DESIGNED : HT. SATO 14.10.23			CODE NO. CL665-0005-9-62		
DRAWN : MI. SAKIMURA 14.10.22					

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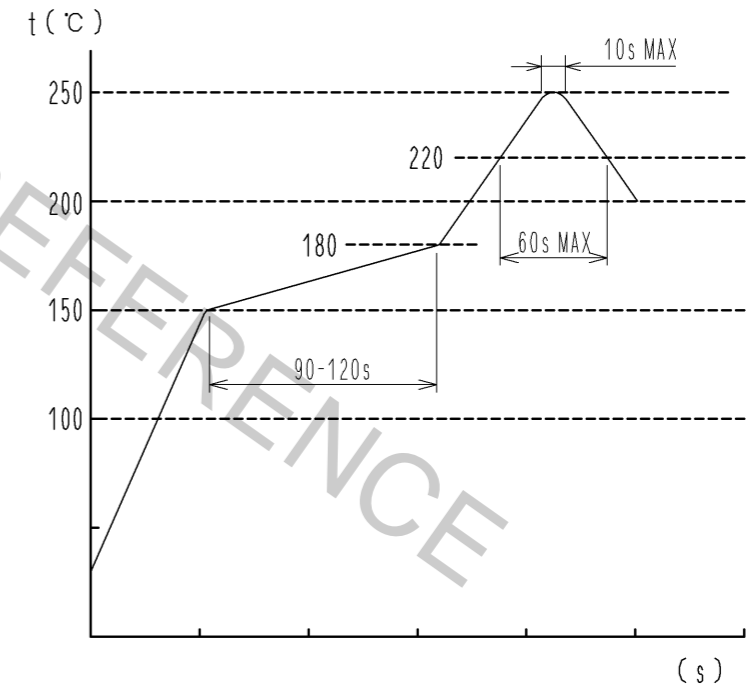
RECOMMENDED PCB LAYOUT
(MOUNTING SURFACE SIDE) (FREE)



RECOMMENDED METAL MASK (FREE)
THICKNESS : 0.1mm



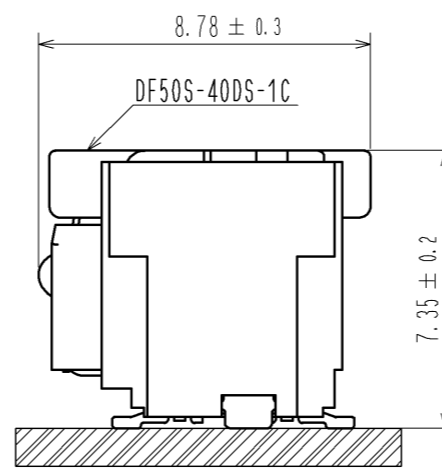
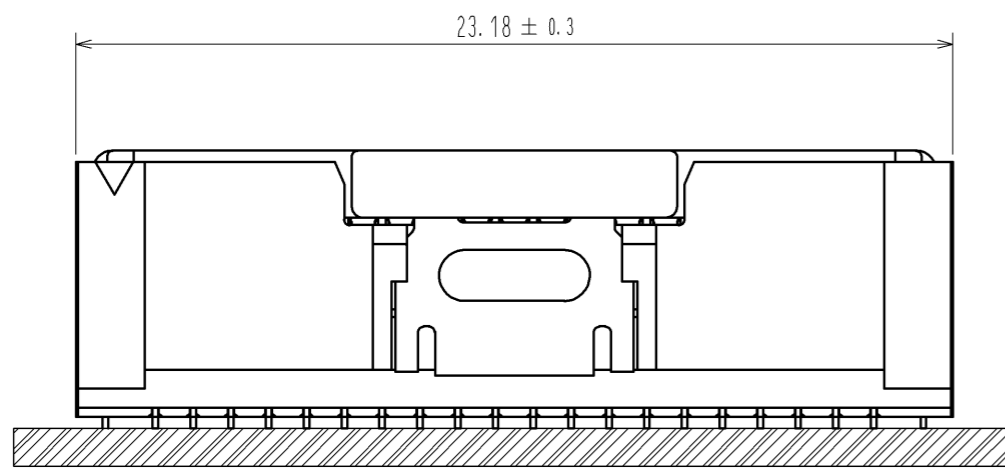
REFLOW TEMPERATURE PROFILE
USING LEAD-FREE SOLDER PASTE(REFERENCE)



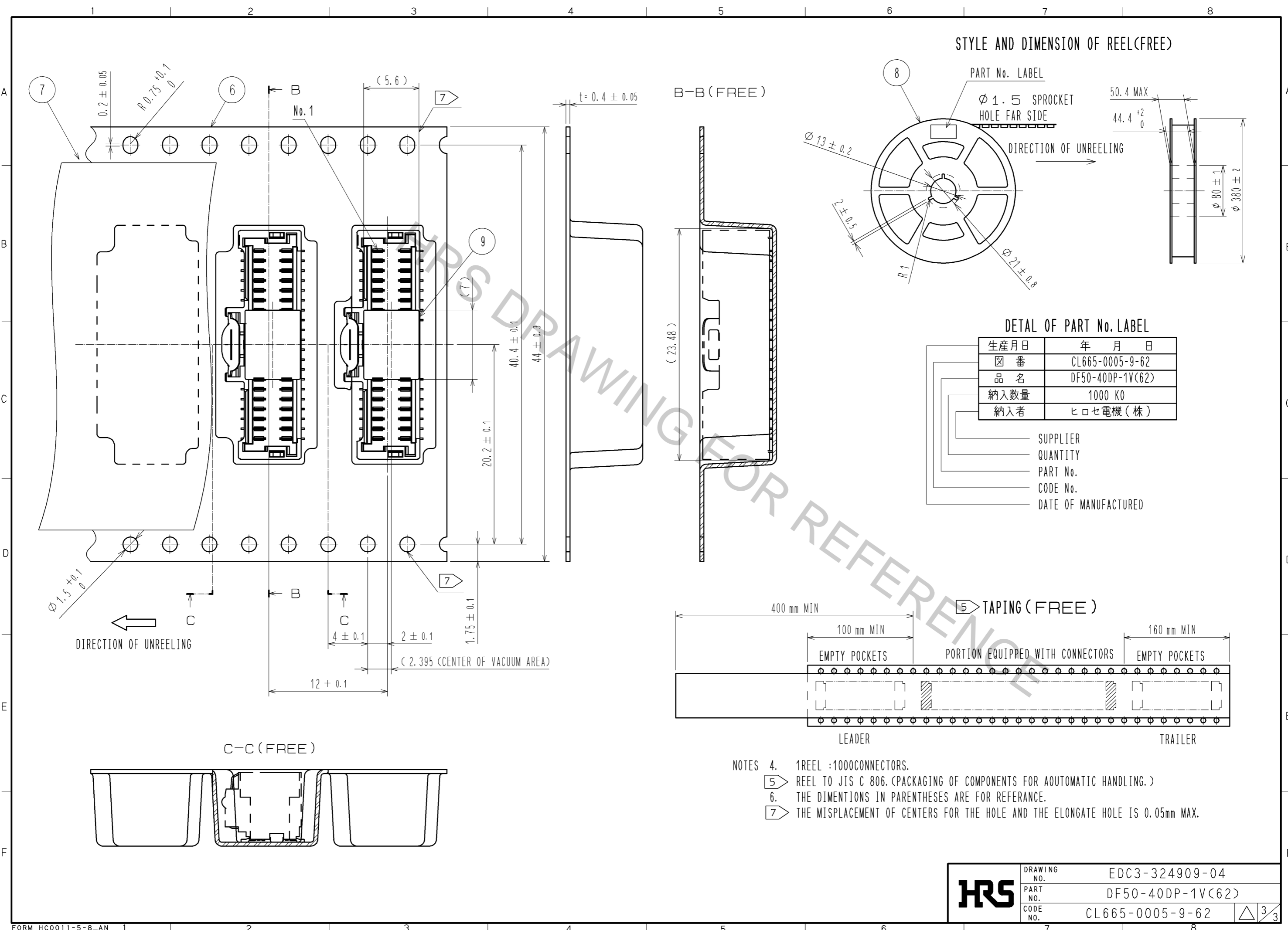
NUMBER OF REFLOW CYCLES : 2 CYCLES MAX.
THE TEMPERATURE OF THIS PROFILE IS MEASURED ON THE LEAD TERMINAL.

WE RECOMMEND PERFORMING AN EVALUATION UNDER THE MOUNTING
CONDITIONS YOU WILL BE USING BECAUSE IT COULD BE AFFECTED
BY ANY CONDITION:TYPE OF SOLDER PASTE, SIZE OF PCB, MOUNTING
METAL etc.

MATING FIGURE (5 : 1)



HRS	DRAWING NO.	EDC3-324909-04
	PART NO.	DF50-40DP-1V(62)
	CODE NO.	CL665-0005-9-62
		△ 2/3



HRS	DRAWING NO.	EDC3-324909-04
	PART NO.	DF50-40DP-1V(62)
	CODE NO.	CL665-0005-9-62
		△ 3/3